

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
650V	180mΩ@10V	20A

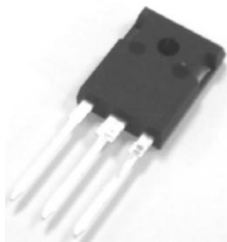
Feature

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Ultra low gate charge cause lower driving requirements

Application

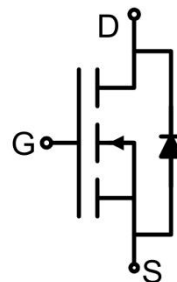
- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

Package



TO-247AB

Circuit diagram



Marking



Absolute maximum ratings (T_C=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} =0V)	V _{DS}	650	V
Gate-Source Voltage (V _{DS} =0V) AC (f > 1Hz)	V _{GS}	±30	V
Gate-Source Voltage (V _{DS} =0V) DC	V _{GS}	±20	V
Continuous Drain Current	I _D	20	A
Continuous Drain Current (T _C =100°C)	I _D (100°C)	14	A
Pulsed Drain Current ¹⁾	I _{DM}	60	A
Power Dissipation	P _D	194	W
Thermal Resistance Junction to Case	R _{θJC}	0.77	°C/W
Operating Junction Temperature	T _J	-55 ~ +175	°C
Storage Temperature	T _{STG}	-55 ~ +175	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	650			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =650V, V _{GS} =0V, T _C =25℃			1	μA
Gate-body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	3	3.5	4	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =10V, I _D =10A		160	180	mΩ
Dynamic characteristics ²⁾						
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, f =1MHz		1550		pF
Output Capacitance	C _{oss}			60		
Reverse Transfer Capacitance	C _{rss}			5		
Total Gate Charge	Q _g	V _{DS} =480V, V _{GS} =10V I _D =10.5A		28.5		nC
Gate-Source Charge	Q _{gs}			11.7		
Gate-Drain Charge	Q _{gd}			5		
Turn-on delay time	t _{d(on)}	V _{DS} =380V, V _{GS} =10V, I _D =10A R _G =1.7Ω		32		nS
Turn-on rise time	t _r			18		
Turn-off delay time	t _{d(off)}			90		
Turn-off fall time	t _f			8		
Source-Drain Diode characteristics						
Diode Forward Current	I _S	T _C =25℃			20	A
Diode Forward voltage	V _{SD}	V _{GS} =0V, I _S =20A, T _J =25℃			1.2	V
Reverse Recovery Time	T _{rr}	I _F =10A, di/dt =100A/μs T _J =25℃		300		nS
Reverse Recovery Charge	Q _{rr}			4.5		μC
Peak Reverse Recovery Current	I _{rrm}			30		A

Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2) Guaranteed by design, not subject to production testing.

Typical Characteristics

Figure1. Safe operating area

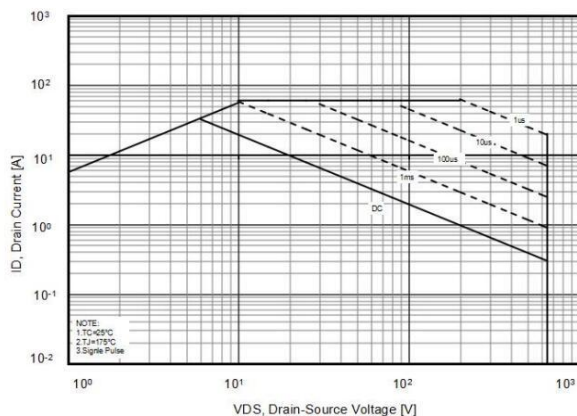


Figure2. Capacitance

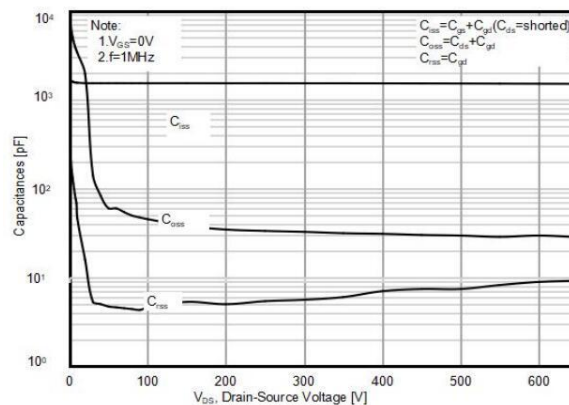


Figure3. Transfer characteristics

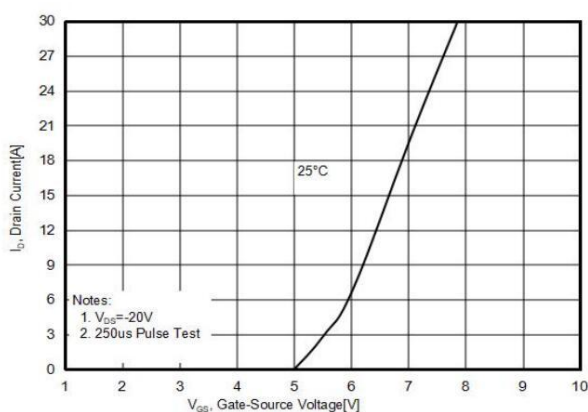


Figure4. Output characteristics

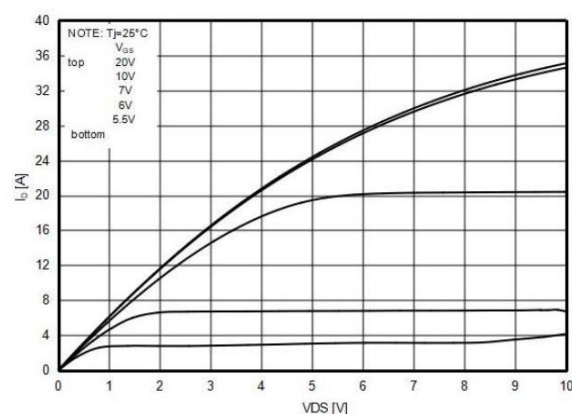


Figure5. $R_{DS(ON)}$ vs Junction Temperature

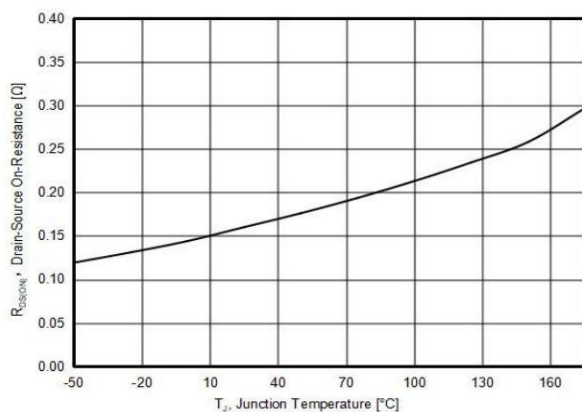
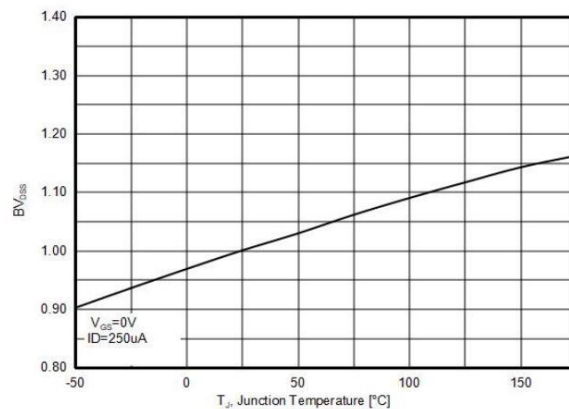


Figure6. BV_{DSS} vs Junction Temperature



Typical Characteristics

Figure7. Maximum I_D vs Junction Temperature

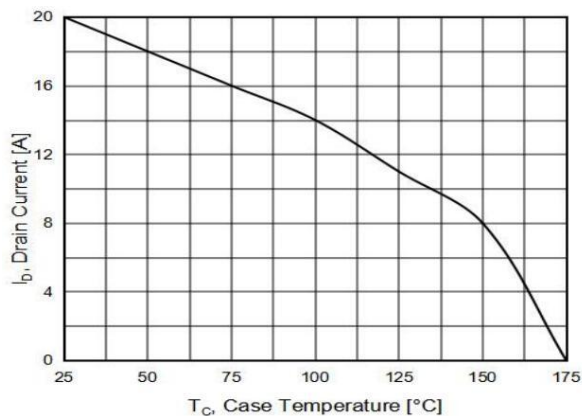


Figure8. Gate charge waveforms

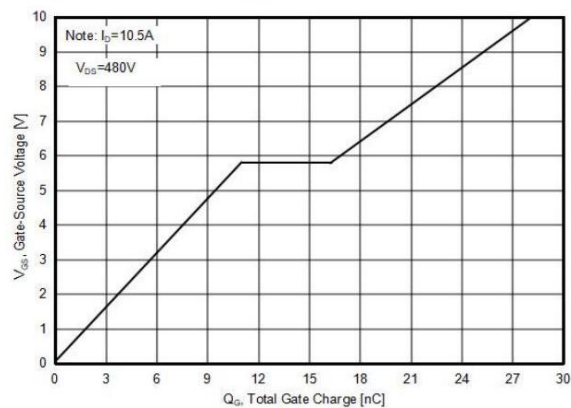


Figure9. Static drain-source on resistance

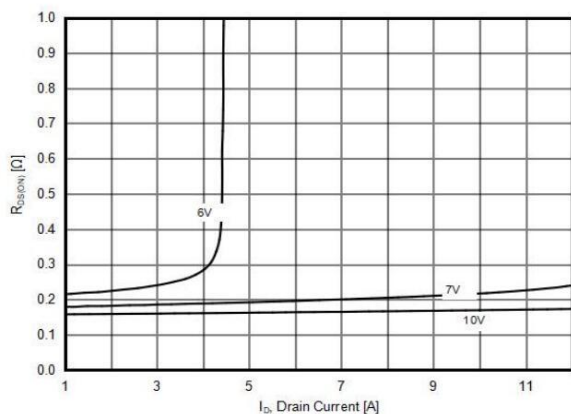
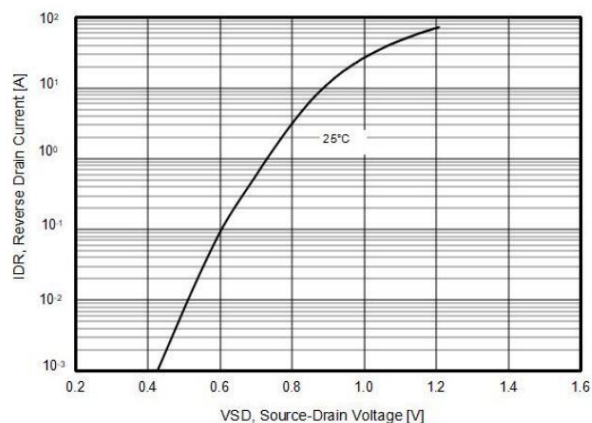
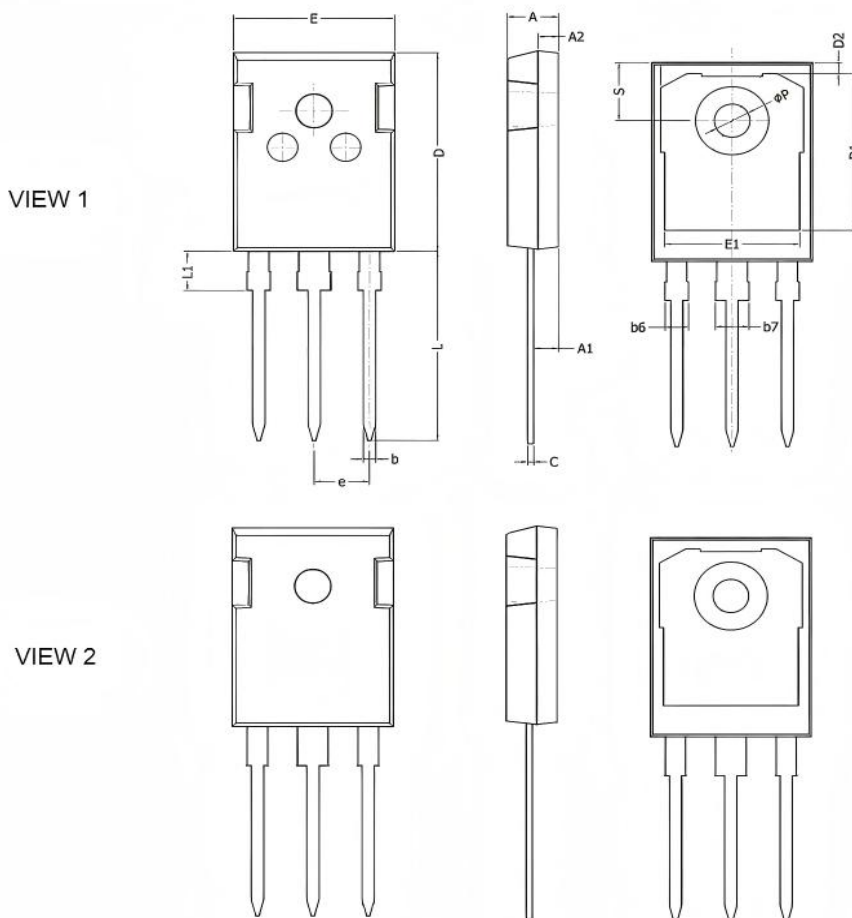


Figure10. Source-Drain Diode Forward Voltage



TO-247AB Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.830	5.210	0.190	0.205
A1	2.290	2.540	0.090	0.100
A2	1.900	2.160	0.075	0.085
b	1.070	1.330	0.042	0.052
b6	1.91	2.410	0.075	0.095
b7	2.87	3.380	0.113	0.133
C	0.550	0.680	0.022	0.027
D	20.800	21.100	0.819	0.831
D1	16.250	17.650	0.640	0.695
D2	0.950	1.350	0.037	0.053
E	15.700	16.130	0.618	0.635
E1	12.380	13.500	0.487	0.531
e	5.440 BSC.		0.214 BSC.	
L	19.800	20.320	0.780	0.800
L1	4.100	4.400	0.161	0.173
P	3.400	3.650	0.134	0.144
S	6.000	6.400	0.236	0.252